

NEGATIVE PHOTSENSITIVE RESIN COMPOSITION, NEGATIVE PHOTSENSITIVE RESIN COMPOSITION COATING, NEGATIVE PHOTSENSITIVE RESIN COMPOSITION FILM, cured layer, AND SEMICONDUCTOR DEVICE USING THESE

ABSTRACT

Provided is a resin composition which exhibits excellent pattern processability in the form of a thick film and does not cause organic deposits even if processed on a substrate having an aluminum pad electrode. This negative photosensitive resin composition contains: at least one polymer compound selected from the group consisting of a polyamide, a polyimide, a polyamideimide and a polybenzoxazole as a component (A); a cationic polymerizable compound as a component (B); and a cationic photopolymerization initiator as a component (C). The negative photosensitive resin composition is characterized in that the content of fluorine atoms in the component (A) is 1 mass% or less.

[No Figure]